

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SEONG CHEOL KIM	05/28/2007
MYUNG GEUN PARK	05/28/2007
RECEIVING PARTY DATA	
Name:	HYNIX SEMICONDUCTOR INC.
Street Address:	San 136-1, Ami-ri, Bubal-eub, Icheon-si
City:	Kyoungki-do
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11760048
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	CU-5727 WWP/NK
NAME OF SUBMITTER:	Woochoon W. Park
Total Attachments: 2 source=cu5727assign#page1.tif source=cu5727assign#page2.tif	

CH \$40.00 11760048

UNITED STATES OF AMERICA
ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

ASSIGNOR:

Name : Seong Cheol KIM
Address : 308-404, Green Ville, 656 Seok-dong, Jinhae-si, Gyeongsangnam-do, Korea
Name : Myung Geun PARK
Address : Da-202, 162-4, Godeok-dong, Gangdong-gu, Seoul, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

ASSIGNEE:

Name : Hynix Semiconductor Inc.
Address : San 136-1, Ami-ri, Bubal-eub, Icheon-si, Kyoungki-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:

METHOD FOR MANUFACTURING STRIP LEVEL SUBSTRATE WITHOUT WARPAGE AND METHOD FOR MANUFACTURING SEMICONDUCTOR PACKAGE USING THE SAME

(TITLE)

and which is found in *(check one applicable item below)*

- U.S. patent application executed on even date herewith
 U.S. Application Serial No. _____ filed on _____

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify

as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

May 28, 2007

Date

Seong Cheol Kim
INVENTOR: Seong Cheol KIM

May 28, 2007

Date

Myung Geun Park
INVENTOR: Myung Geun PARK

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한국특허청
2007.05.28